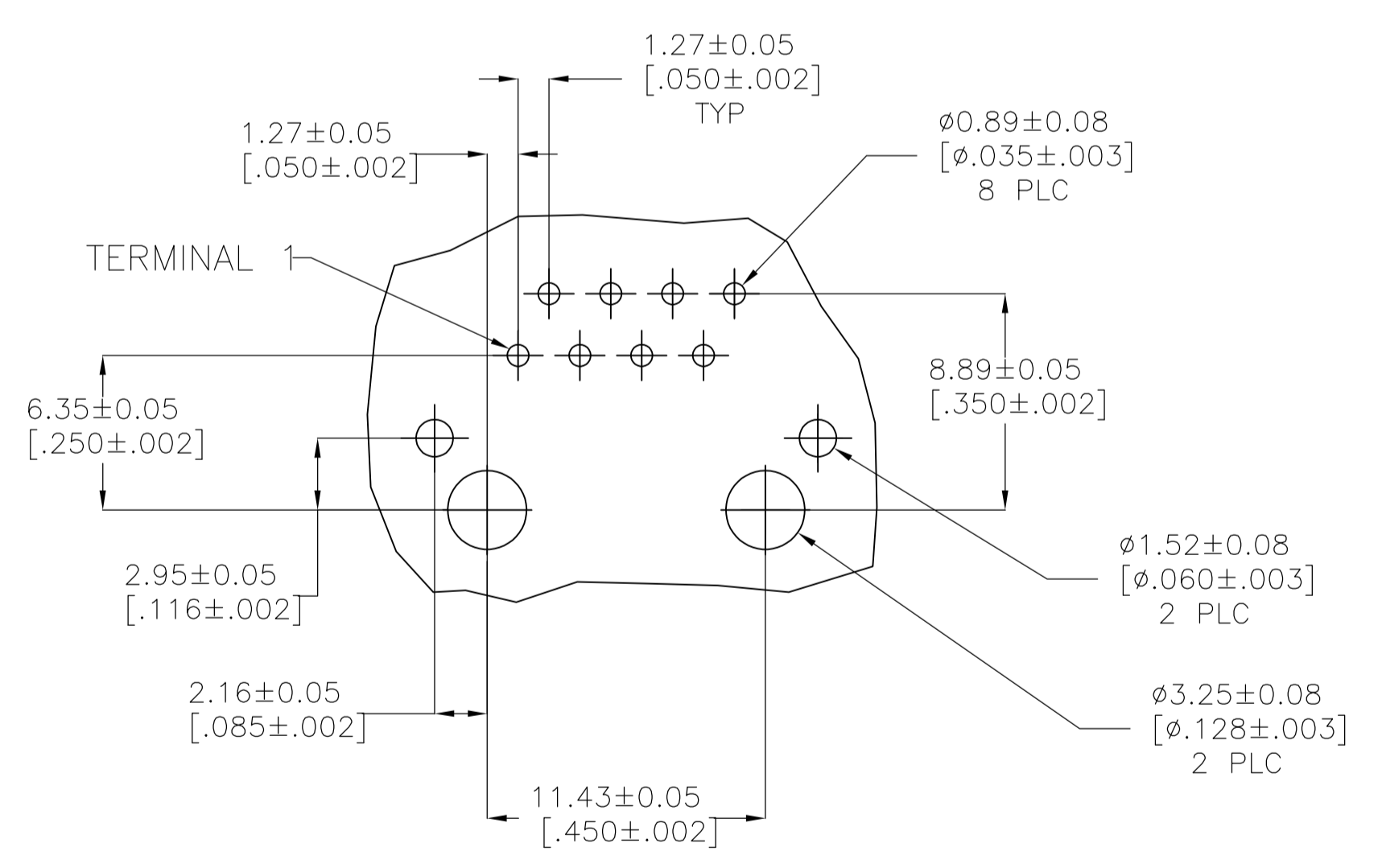
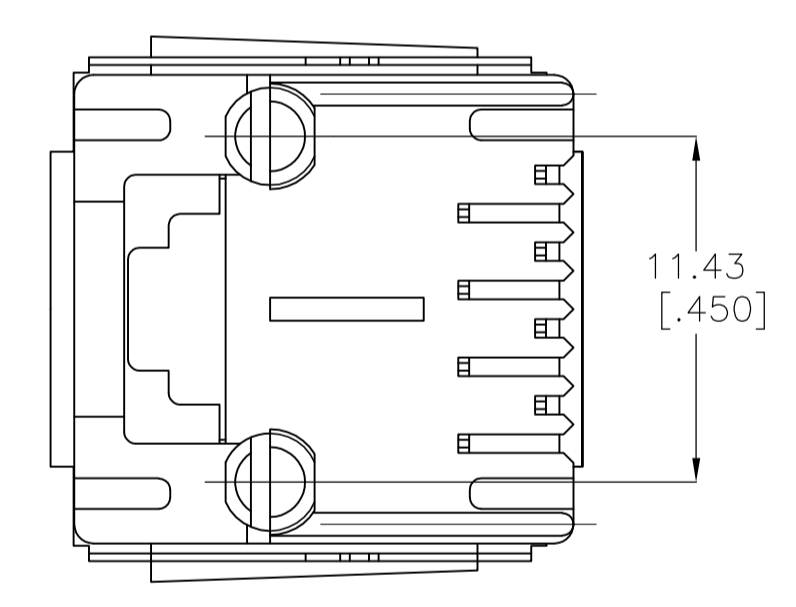
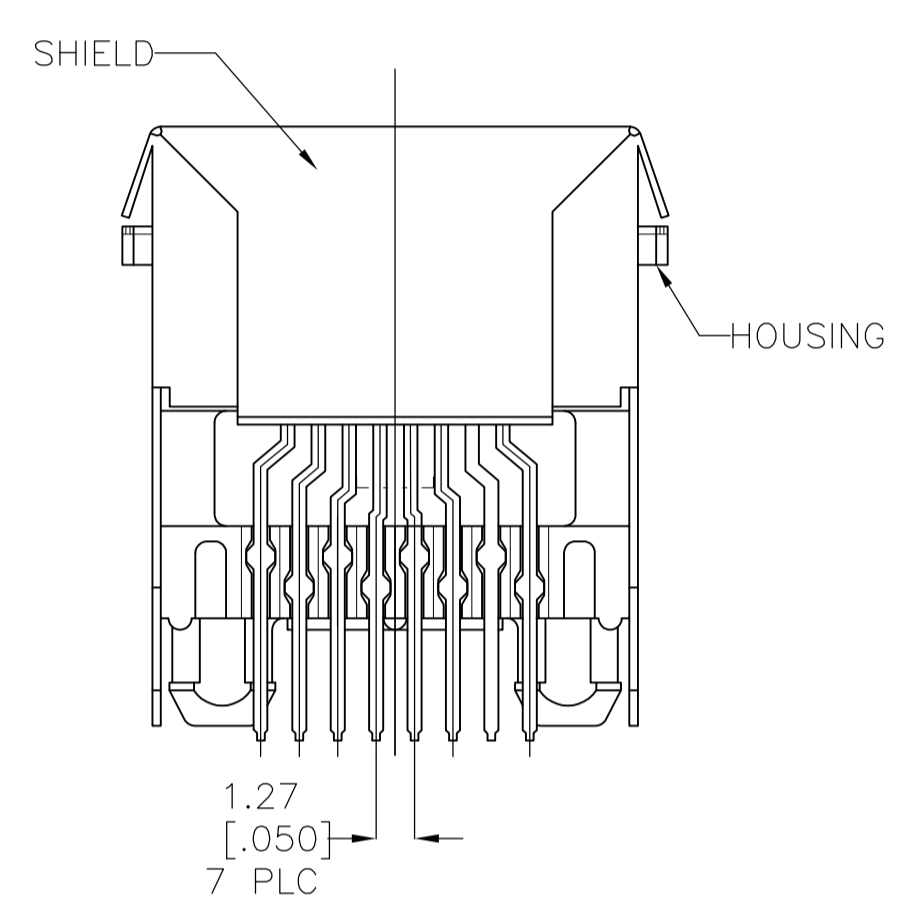
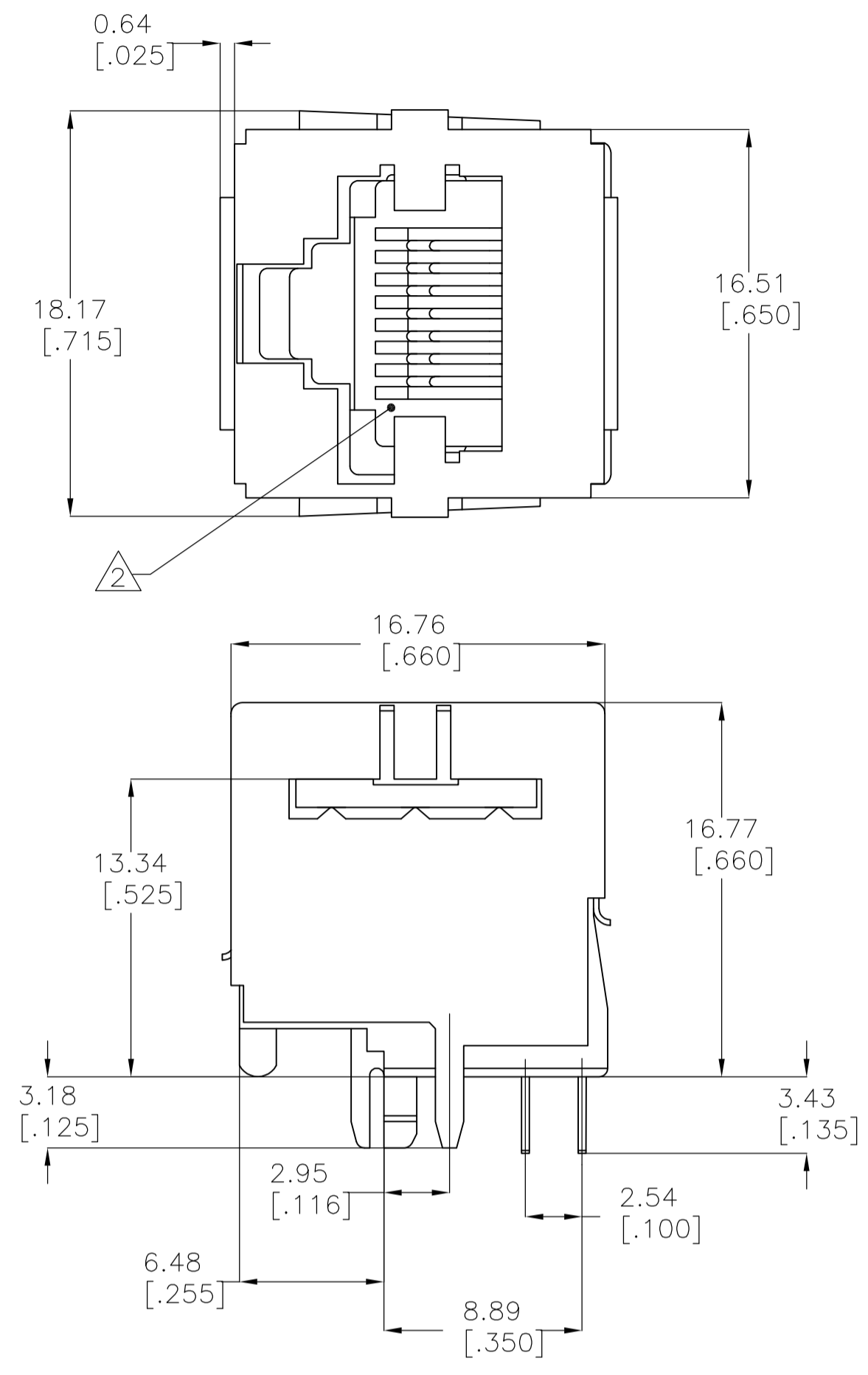
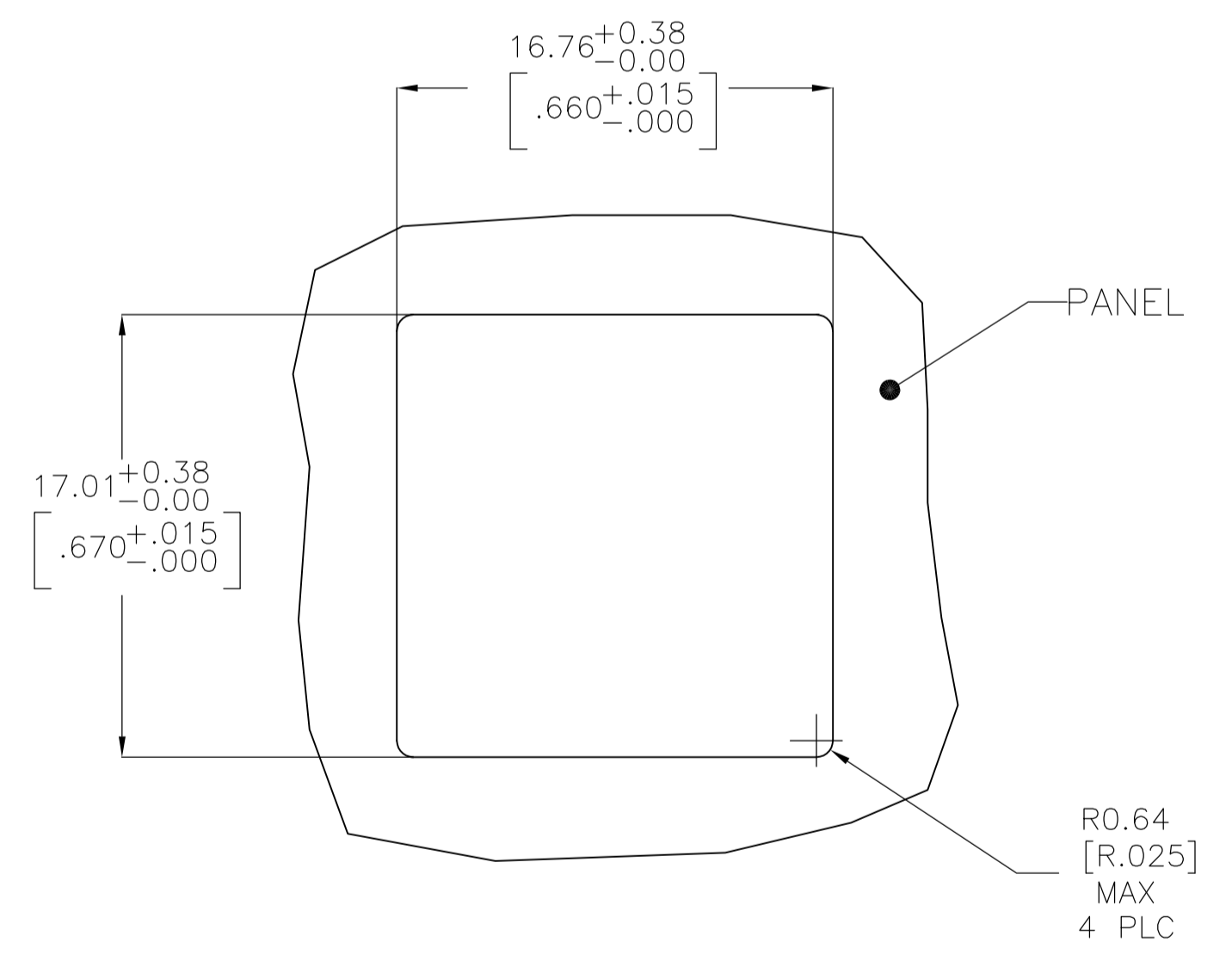


LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DMN	APVD		
B		ECO-07-021363	25SEPT07	LAM	PR		



RECOMMENDED PRINTED  
CIRCUIT BOARD LAYOUT  
COMPONENT SIDE SHOWN



RECOMMENDED PANEL  
CUTOUT

- MATERIAL:  
 HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK  
 TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81μm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MIN THICK NICKEL UNDERPLATE  
 SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0μm [.000120] MIN THICK REFLOWED TIN.

2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

1888412-1  
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN D. STRAUSSER / L.A. MAYER 07MAR2006		Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 07MAR2006	
0 PLC ± - 1 PLC ± - 2 PLC ± - 3 PLC ± 0.13[.005] 4 PLC ± - ANGLES ± -		PRODUCT SPEC 108-1163 APPLICATION SPEC 114-2048		NAME MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS SIZE CAGE CODE DRAWING NO A1 00779 C=1888412	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT -	
		CUSTOMER DRAWING		SCALE 4:1 SHEET 1 OF 1 REV B	

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)